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MMSZ4684

General Description

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

Features

- Compact surface mount with same footprint as mini-melf
- 500mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16kV) per Human Body Model

Ordering

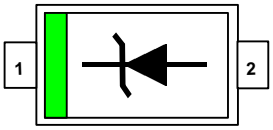
- 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

Absolute Maximum Ratings (note 1) T_A=25°C unless otherwise noted

Symbol	Parameter	Value	Units
T_{STG}	Storage Temperature	-55 ~ 150	°C
T_J	Maximum Junction Temperature	-55 ~ 150	°C
P_D	Total Power Dissipation at 25°C Derate above 25°C	500 6.7	mW mW/°C
R_{QJA}	Thermal Resistance Junction to Ambient	340	°C/W
R_{QJL}	Thermal Resistance Junction to Lead	150	°C/W
ΔV_Z	Maximum Voltage Change (note 2)	950	mV
Lead Solder Temperature (Max 10 second duration)		260	°C
Nominal Zener Voltage (V_Z) at 50µA		3.3	V

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
Note 2: Voltage change is equal to the difference between V_Z at 100µA and V_Z at 10µA.

Top Mark: CK
1: Cathode
2: Anode



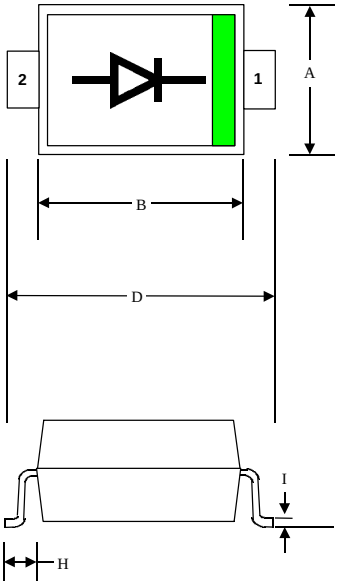
Electrical Characteristics T_A=25°C unless otherwise noted

Symbol	Characteristics	Test Conditions	Min.	Max.	Units
V_Z	Zener Voltage	I_{ZT} = 50µA D.C	3.14	3.47	V
I_R	Reverse Leakage	V_R = 1.5V		7.5	µA
V_F	Forward Voltage	I_F = 10mA		900	mV
ΔV_Z	Delta Zener Voltage (Note 2)	I_{ZT} = 100µA to 10µA		950	mV

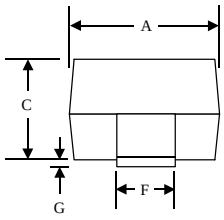
SOD-123 PACKAGE

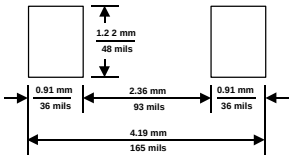
PACKAGE CODE = (D6)
Fairchild Semiconductor's Criteria

Corrected March 11, 1998



Actual Size DIM	MIN (mils)	MAX (mils)	MIN (mm)	MAX (mm)
A	55	71	1.400	1.800
B	100	112	2.550	2.850
C	34.6	46	0.880	1.180
D	141.7	153.5	3.600	3.900
E	----	----	-------	-------
F	21.5	27.5	0.546	0.70
G	0.5	4	0.0135	0.1015
H	12.7	----	0.322	-------
I	3.7	7.7	0.095	0.195





SOD-123 LAND PADS

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.